

## Mobile DiskOnChip G3 512Mbit with NAND MLC and x2 Technology



### Description

M-Systems is announcing a new member of the DiskOnChip family, Mobile DiskOnChip G3 512Mbit with NAND MLC and x2 technology, available in a 7x10 mm FBGA package and a standard 12x20 mm TSOP-I package.

### Ordering Information and Availability

The table below shows the ordering information and availability of the new Mobile DiskOnChip G3 512Mbit device.

Capacity	Package	Temperature Range <sup>1</sup>	Type	Order Information	Availability <sup>2</sup>
512Mbit (64MByte)	12x20 mm TSOP-I (48-pin)	Commercial	Regular	MD4811-d512-V3Q18	ES – 15 May, 2003 MP – 1 September, 2003
		Extended	Regular	MD4811-d512-V3Q18-X	
		Commercial	Lead-Free	MD4811-d512-V3Q18-P	
		Extended	Lead-Free	MD4811-d512-V3Q18-X-P	
	7x10 mm FBGA (85-ball)	Commercial	Regular	MD4832-d512-V3Q18	
		Extended	Regular	MD4832-d512-V3Q18-X	
		Commercial	Lead-Free	MD4832-d512-V3Q18-P	
		Extended	Lead-Free	MD4832-d512-V3Q18-X-P	
N/A	7x10 mm FBGA (85-ball)	N/A	Daisy-Chain	MD4832-d00-DAISY	Now

1. Commercial (0°C - 70°C), Extended (-40°C - 85°C)

2. ES – Engineering Samples; MP – Mass Production

### Software Compatibility

Mobile DiskOnChip G3 is supported by TrueFFS version 6.1.

Note: TrueFFS 6.1 currently does not support DiskOnChip Plus devices.

### Hardware Compatibility

Mobile DiskOnChip G3 is hardware compatible with previous DiskOnChip versions, as follows:

1. Mobile DiskOnChip G3 in a TSOP package is compatible with previous DiskOnChip TSOP versions (such as Mobile DiskOnChip Plus).
2. Mobile DiskOnChip G3 in a 7x10 mm FBGA package is backwards compatible with previous DiskOnChip versions in a 9x12 mm (F)BGA package, assuming that the board design for the 9x12 (F)BGA device was prepared according to the guidelines detailed in application note AP-DOC-067, *Preparing your PCB Footprint for the DiskOnChip BGA Migration Path*.

### How to Contact Us

Please contact your M-Systems representative or visit M-Systems' website ([www.m-sys.com](http://www.m-sys.com)) for any further information or assistance.

Ariel Kira ([ariel.kira@m-sys.com](mailto:ariel.kira@m-sys.com))

DiskOnChip Product Manager

DiskOnChip Business Unit